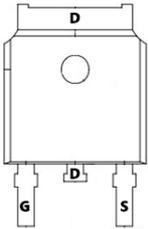


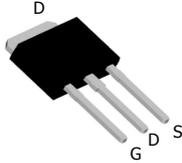
**TMN10015YS**

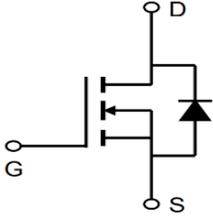
**N-Channel Enhancement Mosfet**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 100V</math> <math>I_D = 15A</math>  <math>R_{DS(ON)} = 75m\Omega(Typ.) @ V_{GS} = 10V</math></p> <p>100% UIS Tested                  100% <math>R_g</math> Tested</p> 
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**Y:TO-251S-3L**





Marking: 15N10

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	15	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	8	A
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	2.4	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	20	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	6.1	mJ
$I_{AS}$	Avalanche Current	10	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>3</sup>	30	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	6.6	°C/W

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=100V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	$V_{GS}=10V, I_D=5A$	-	75	110	m $\Omega$
		$V_{GS}=4.5V, I_D=3A$	-	96	140	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$	-	765	-	pF
$C_{oss}$	Output Capacitance		-	38	-	pF
$C_{riss}$	Reverse Transfer Capacitance		-	33	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=50V, I_D=2A,$ $V_{GS}=10V$	-	18	-	nC
$Q_{gs}$	Gate-Source Charge		-	2.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50V, I_D=3A,$ $R_G=1.8\Omega, V_{GS}=10V$	-	7.5	-	ns
$t_r$	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
$t_f$	Turn-off Fall Time		-	9	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	10	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	40	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=10A$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=3A, di/dt=100A/\mu s$	-	21	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	22	-	nC

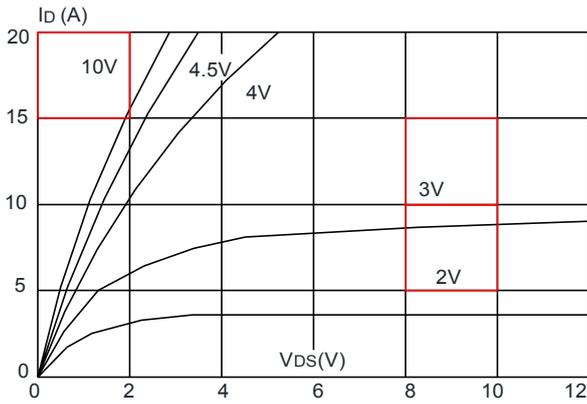
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=4A$

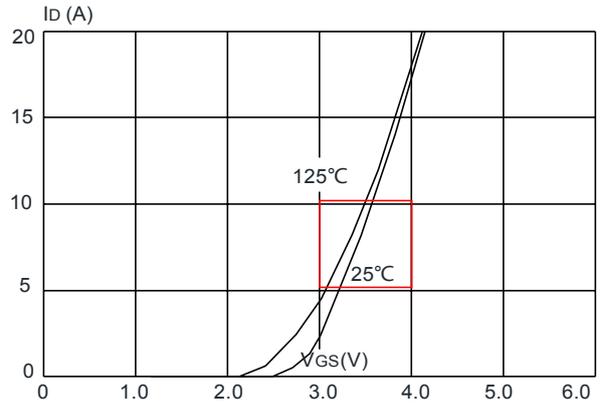
3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

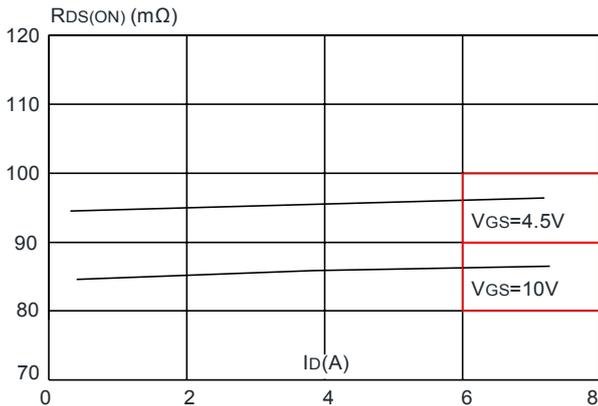
**Figure 1: Output Characteristics**



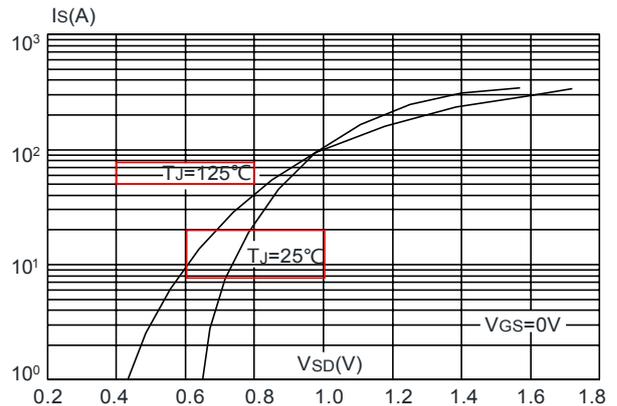
**Figure 2: Typical Transfer Characteristics**



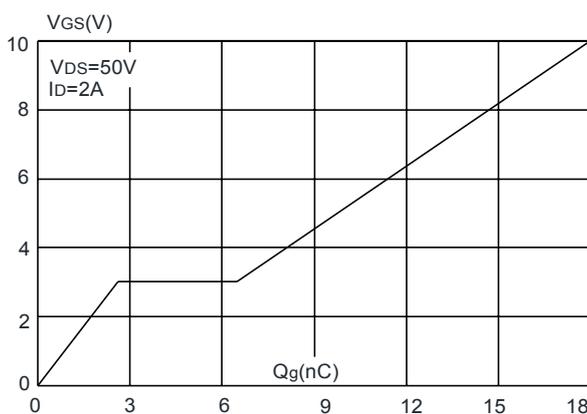
**Figure 3: On-resistance vs. Drain Current**



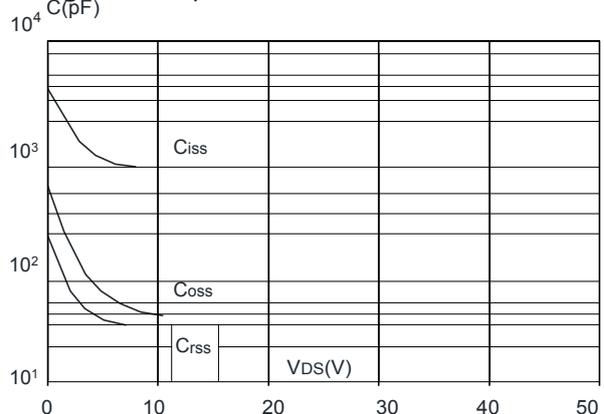
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**



**Figure 6: Capacitance Characteristics**



TMN10015YS

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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

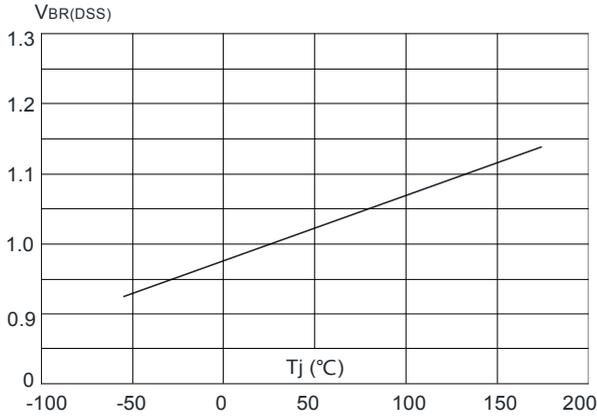


Figure 8: Normalized on Resistance vs. Junction Temperature

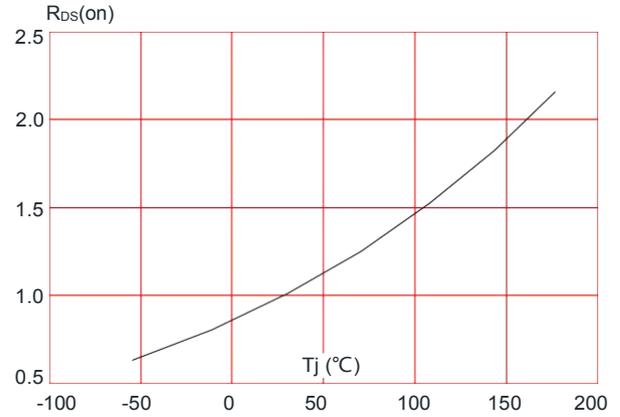


Figure 9: Maximum Safe Operating Area

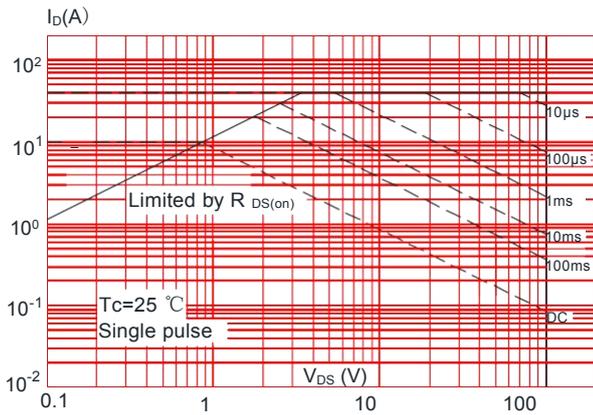


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

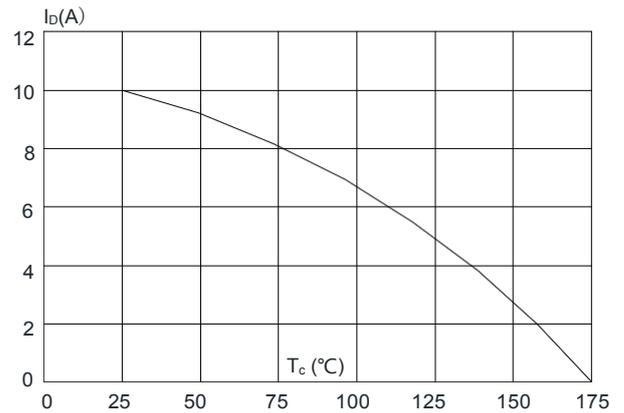
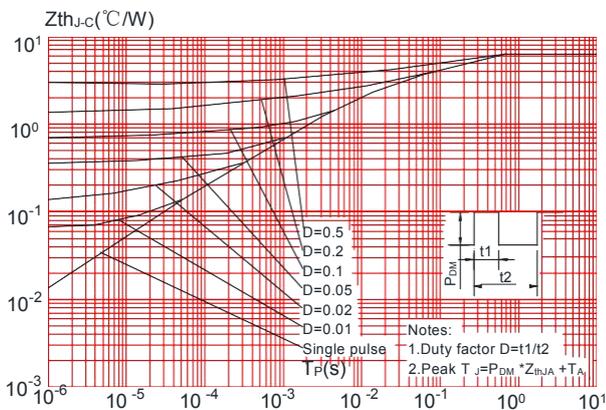


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



# Package Information:TO-251S-3L

UNIT: mm

SYMBOL	min	nom	max
A	2.20		2.40
b	0.50		0.85
C	0.45	0.50	0.60
D	6.50		6.70
D1	5.10		5.50
E	5.9		6.20
e	2.18	2.29	2.38
L	11.00		12.40
L1	4.8		5.3
L2	3.5		4.2

